

AMENDMENTS TO THE CLAIMS, COMPLETE LISTING OF CLAIMS
IN ASCENDING ORDER WITH STATUS INDICATOR

Please amend the following claims as indicated.

1. (Currently Amended) A process for a molded article which is shaped by molding, said process comprising:

shaping a material comprising a thermoplastic resin composition containing 100 parts by weight of a ~~thermosetting-an-amorphous thermoplastic~~ resin and 0.1 to 100 parts by weight of an inorganic compound dispersed in said ~~thermosetting-thermoplastic~~ resin in a die by transferring a shape of the die the inorganic compound being at least one of silica and laminar silicate, and the dispersion particle diameter of the silica being 2 μ m or less and the laminar silicate having an average length of 0.01 to 3 μ m and;

curing the material after shaping to obtain the molded article wherein ~~characterized in that~~ not less than 75% of the shape of ~~the a-molded~~ article ~~molded before curing~~ is maintained at temperatures above the glass transition point of said thermoplastic resin.

2. (Currently Amended) A-~~The process for a molded article which is shaped by molding according to claim 1, wherein the thermoplastic resin composition containing 100 parts by weight of is an~~ crystalline thermoplastic resin and 0.1 to 100 parts by weight of an inorganic compound dispersed in said thermoplastic resin, characterized in that not less than 75% of the shape of a molded article is maintained at temperatures above the melting point of said thermoplastic resin.

3. (Canceled).

4. (Currently Amended) The process for a molded article which is shaped by molding thermoplastic resin composition according to claim 1 or 2, wherein said inorganic compound is an inorganic compound containing silicon and oxygen as a constituent element ~~elements~~.

5. (Currently Amended) ~~The process for a molded article which is shaped by molding thermoplastic resin composition~~ according to claim 1 or 2, wherein said inorganic compound is laminar silicate.

6. (Currently Amended) ~~A material for substrates, characterized in that said material is composed by using the thermoplastic resin composition substrate comprising the molded article obtained by the process for the molded article~~ according to claim 1 or 2.

7. (Previously Presented) ~~A film for substrates comprising the molded article obtained by the process for the molded article, characterized in that said film is composed by using the thermoplastic resin composition~~ according to claim 1 or 2.

8. (Canceled).

9. (Canceled).

10. (Currently Amended) ~~The process for a molded article which is shaped by molding thermoplastic resin composition~~ according to claim 4, wherein said inorganic compound is laminar silicate.

11. (Canceled).

12. (Currently Amended) ~~A material for substrates, characterized in that said material is composed by using the thermoplastic resin composition substrate comprising the molded article obtained by the process for the molded article~~ according to claim 4.

13. (Currently Amended) ~~A material for substrates, characterized in that said material is composed by using the thermoplastic resin composition substrate comprising the molded article obtained by the process for the molded article~~ according to claim 5.

14. (Canceled).

15. (Currently Amended) A film for substrates comprising the molded article obtained by the process for the molded article, ~~characterized in that said film is composed by using the thermoplastic resin composition according to claim 4.~~

16. (Currently Amended) A film for substrates comprising the molded article obtained by the process for the molded article, ~~characterized in that said film is composed by using the thermoplastic resin composition according to claim 5.~~